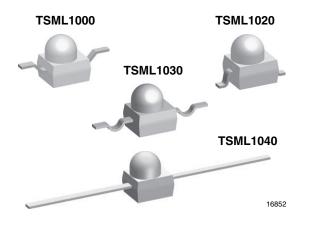
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# TSML1000, TSML1020, TSML1030, TSML1040

**Vishay Semiconductors** 

# High Power Infrared Emitting Diode, 940 nm, GaAlAs, MQW



## DESCRIPTION

TSML1000 is an infrared, 940 nm emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed molded in a clear, untinted plastic package (with lens) for surface mounting (SMD).

## FEATURES

- Package type: surface mount
- Package form: GW, RGW, yoke, axial
- Dimensions (L x W x H in mm): 2.5 x 2 x 2.7
- Peak wavelength:  $\lambda_p = 940 \text{ nm}$
- High radiant power
- · High radiant intensity
- Angle of half intensity:  $\varphi = \pm 12^{\circ}$
- Low forward voltage
- Suitable for high pulse current operation
- · Good spectral matching with Si photodetectors
- · Versatile terminal configurations
- Package matches with detector TEMT1000
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### APPLICATIONS

- For remote control
- · Punched tape readers
- Encoder
- Photointerrupters

PRODUCT SUMMARY				
COMPONENT	l <sub>e</sub> (mW/sr)	φ (deg)	λ <sub>P</sub> (nm)	t <sub>r</sub> (ns)
TSML1000	11	± 12	940	15
TSML1020	11	± 12	940	15
TSML1030	11	± 12	940	15
TSML1040	11	± 12	940	15

#### Note

• Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS PACKA			
TSML1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing		
TSML1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing		
TSML1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke		
TSML1040	Bulk	MOQ: 1000 pcs, 1000 pcs/bulk	Axial leads		

#### Note

• MOQ: minimum order quantity

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COMPLIANT



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ABSOLUTE MAXIMUM RATINGS (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		I <sub>F</sub>	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \ \mu s$	I <sub>FM</sub>	200	mA	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1.0	А	
Power dissipation		Pv	190	mW	
Junction temperature		Тj	100	°C	
Operating temperature range		T <sub>amb</sub>	-40 to +85	°C	
Storage temperature range		T <sub>stg</sub>	-40 to +100	°C	
Soldering temperature	t ≤ 5 s	T <sub>sd</sub>	< 260	°C	
Thermal resistance junction/ambient	Soldered on PCB, pad dimensions: 4 mm x 4 mm	R <sub>thJA</sub>	400	°C	

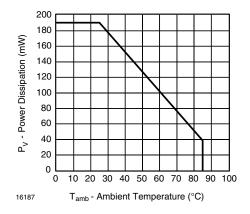


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

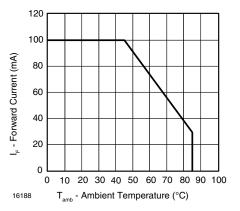


Fig. 2 - Forward Current vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 20 mA, t <sub>p</sub> = 20 ms	V <sub>F</sub>		1.2	1.5	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \ \mu \text{s}$	V <sub>F</sub>		2.2		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>VF</sub>		-1.8		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	Cj		40		pF
Radiant intensity	$I_{\rm F} = 20  {\rm mA},  {\rm t_p} = 20  {\rm ms}$	l <sub>e</sub>	3	11	15	mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	фе		40		mW
Temperature coefficient of $\phi_{e}$	I <sub>F</sub> = 20 mA	TKφ <sub>e</sub>		-0.6		%/K
Angle of half intensity		φ		± 12		deg
Peak wavelength	I <sub>F</sub> = 100 mA	λρ		940		nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ		30		nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 100 mA	ΤΚλρ		0.2		nm/K
Rise time	I <sub>F</sub> = 100 mA	t <sub>r</sub>		15		ns
Fall time	I <sub>F</sub> = 100 mA	t <sub>f</sub>		15		ns

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## BASIC CHARACTERISTICS (T<sub>amb</sub> = 25 °C, unless otherwise specified)

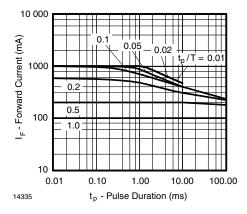


Fig. 3 - Pulse Forward Current vs. Pulse Duration

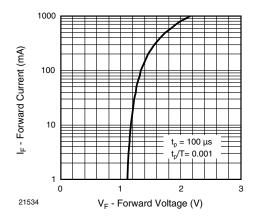


Fig. 4 - Forward Current vs. Forward Voltage

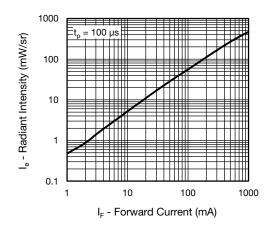


Fig. 5 - Radiant Intensity vs. Forward Current

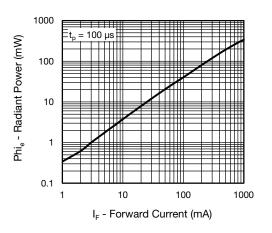


Fig. 6 - Radiant Power vs. Forward Current

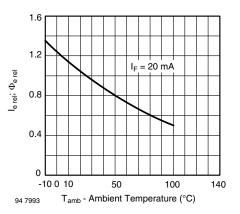


Fig. 7 - Relative Radiant Intensity/Power vs. Ambient Temperature

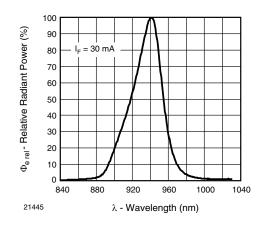


Fig. 8 - Relative Radiant Power vs. Wavelength

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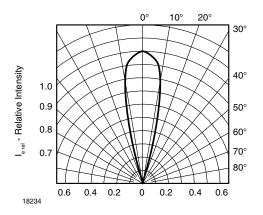


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

#### **PRECAUTIONS FOR USE**

#### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

#### 2. Storage

- Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- Floor life must not exceed 168 h, acc. to JEDEC level 3, J-STD-020.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.

Considering tape life, we suggest to use products within one year from production date.

- If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C  $\pm$  5 °C for 15 h.
- If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

## **REFLOW SOLDER PROFILE**

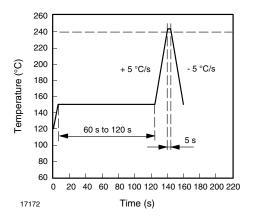


Fig. 10 - Lead Tin (SnPb) Reflow Solder Profile

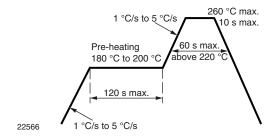


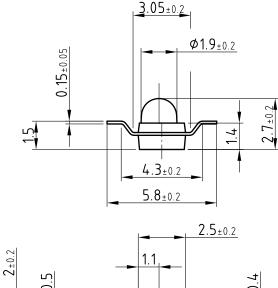
Fig. 11 - Lead (Pb)-Free Reflow Solder Profile acc. J-STD-020

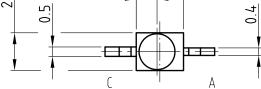


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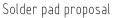
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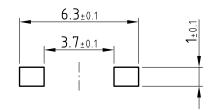






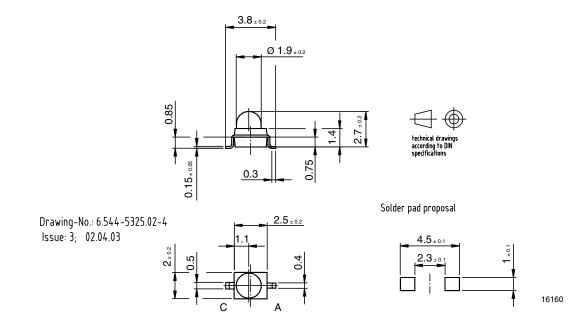
technical drawings according to DIN specifications





Drawing-No.: 6.544-5326.02-4 Issue: 3; 02.04.03 16159

#### PACKAGE DIMENSIONS in millimeters: TSML1020

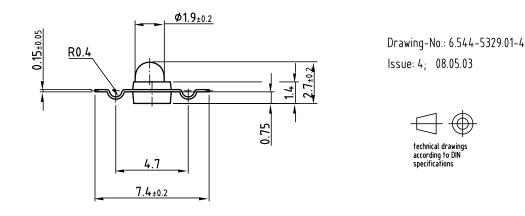


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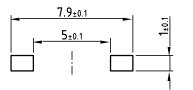
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## PACKAGE DIMENSIONS in millimeters: TSML1030

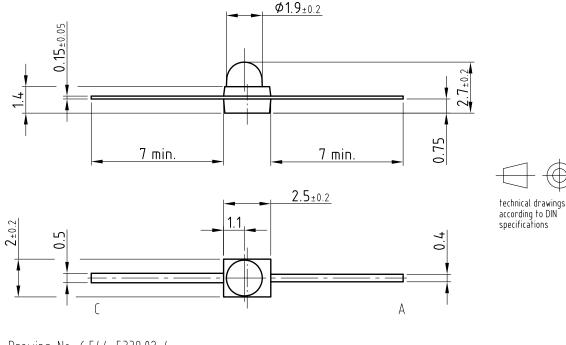


Solder pad proposal



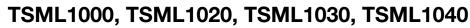
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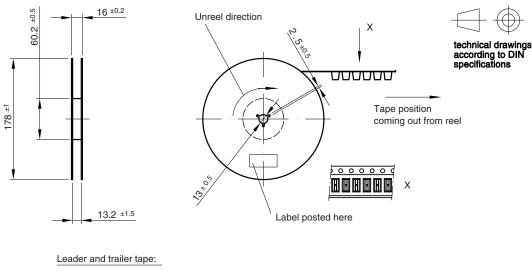
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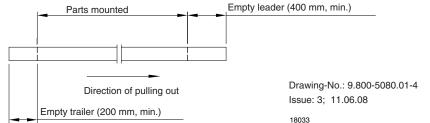
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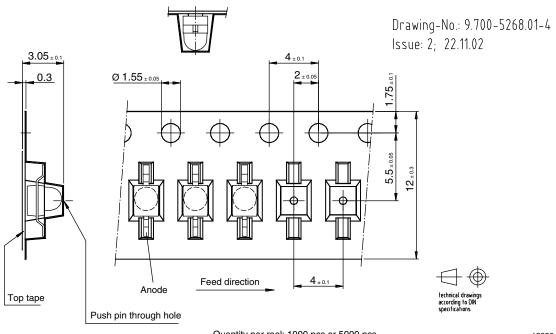


#### **REEL DIMENSIONS** in millimeters





#### TAPING DIMENSIONS in millimeters: TSML1000

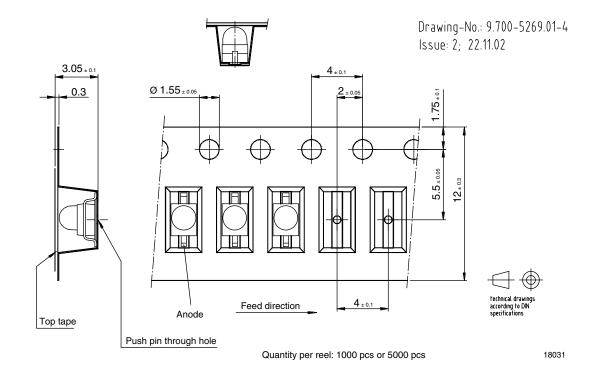


18030

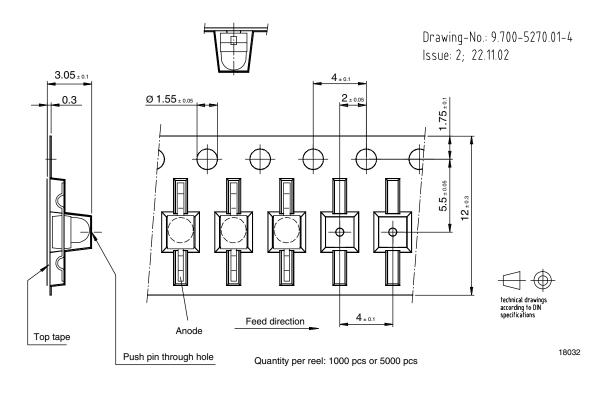
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## TAPING DIMENSIONS in millimeters: TSML1020



## TAPING DIMENSIONS in millimeters: TSML1030



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